

AU526x – Low Noise PLL Based Crystal Oscillator

General Description

The AU526x family of parts is a PLL based crystal oscillator programmable for various output frequencies. The device is user programmable via I2C to provide any frequency between 200KHz to 1GHz. AU526x is a low Noise PLL with Integrated XTAL which provides clocks with Jitter of 110fs(AU5260- Low Jitter) and 85fs(AU5265- Ultra Low Jitter).

AU526x is factory-configurable for a wide variety of user specifications including the I2C address, output format, and OE pin location/polarity .With on chip NVM and factory programming, Aurasemi can satisfy customer requirements with very fast lead times.

Applications:

- . 100G/200G/400G OTN, coherent optics
- · 10G/40G/100G optical ethernet
- · 3G-SDI/12G-SDI/24G-SDI broadcast video
- · Datacenter
- · Test and measurement
- · Clock and data recovery
- · FPGA/ASIC clocking

Features

- I2C programmable to any frequency from 200KHz to 1 GHz.
- Low Jitter : AU5260 110fs Typ Jrms Ultra Low Jitter: AU5265 85fs Typ Jrms (12 kHz – 20 MHz)
- Fractional N fully integrated PLL
- 3.3 V, 2.5 V and 1.8 V VDD supply operation
- I2C Interface supports Standard(100 KHz) and Fast Mode(400 KHz)
- Best in class PSRR performance of -85dBC typical
- Output Driver options: LVPECL, LVDS, HCSL-LP, LVDS-Boost, HCSL,CML.
- +/- 25 ppm stability (-40 °C to 85 °C)
- Package Options: Available in 6pin Plastic
 Package
 - o 5 mm x 3.2 mm
 - $\circ \quad 3.2 \text{ mm x } 2.5 \text{ mm}$
 - o 5 mm x 7 mm (Contact Aurasemi)
 - 2 mm x 2.5 mm (Contact AuraSemi)



Figure 1 Functional Overview



Table of Contents

General Descr	iption	1
Features		1
Table of Conte	nts	2
List of Tables .		3
List of Figures		4
1 Pin Descripti	on	5
2 Electrical Ch	aracteristics	6
3 Serial Progra	amming Interface Description	10
3.1 I2C p	protocol	
3.1.1	Single Byte Write	
3.1.2	Multi Byte Write	
3.1.3	Single Byte Read	
3.1.4	Multi Byte Read	
3.1.5	I2C Bus Timing Specifications	
4 Package Info	ormation	14
5 Output Term	ination Information	
6 Ordering Info	prmation	
7 Revision Hist	tory	



List of Tables

Table 1 Pin Description	5
Table 2 Absolute Maximum Ratings	6
Table 3 Operating Temperature	6
Table 4 DC Electrical Characteristics	6
Table 5 Output RMS Jitter [AU5260]	6
Table 6 Output RMS Jitter [AU5265]	7
Table 7 Clock Output Phase Noise [AU5260]	7
Table 8 Clock Output Phase Noise [AU5265]	7
Table 9 Power Supply Rejection	7
Table 10 Output Clock Specifications	8
Table 11 I2C Bus Timing Specification	13
Table 12 Revision History	19



List of Figures

Figure 1 Functional Overview	1
Figure 2 AU526x Top View	5
Figure 3 I2C Read Operation	. 10
Figure 4 I2C Write Operation	. 11
Figure 5 I2C Timing Waveform	. 13
Figure 6 Package Diagram (3.2 mm x 2.5 mm)	. 14
Figure 7 Package Diagram (5.0 mm x 3.2 mm)	. 14
Figure 8 LVPECL Output Driver used with traditional DC Coupled LVPECL receiver	. 15
Figure 9 LVPECL Output Driver with DC Coupled LVPECL receiver: Thevenin Equivalent	. 15
Figure 10 LVDS Output Driver used with traditional DC Coupled LVDS receiver	. 15
Figure 11 LVDS Output Driver used with AC Coupled terminations for various receivers	. 16
Figure 12 HCSL DC Coupled – Low-Power (HCSL-LP)	. 16
Figure 13 HCSL DC Coupled - Far End Termination	. 17
Figure 14 Output Driver with AC Coupled CML receiver	. 17
Figure 15 Ordering Information	. 18



1 Pin Description



Figure 2 AU526x Top View

Table 1 Pin Description

Pin Name	I/О Туре	Pin No.	Function
OE/NC	Input	1, 2	Selectable by Ordering Information OE = Output Enable; NC = No connect
GND		3	GND
CLKP	Output	4	Clock + for differential Output. Single Ended CMOS Output
CLKN	Output	5	Clock - for differential Output. Single Ended CMOS Output
VDD	Power	6	Chip Power Supply
SDA	Input/Output	7	I2C Serial Data
SCLK	Input	8	I2C Serial Clock

Notes:

The Output Enable Pin can be configured as Active High or Low based on the customer requirement. Refer to the Ordering Information section for more details.



2 Electrical Characteristics

Table 2 Absolute Maximum Ratings

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Core supply voltage		V _{DD}	-0.5		+3.63	V
Input voltage, All Inputs	Relative to GND	V _{IN}	-0.5		+3.63	V
Storage temperature	Non-functional, Non-Condensing	Ts	-55		+150	°C
Programming Temperature		T _{PROG}	+15		+50	°C
Programming Voltage		V _{PROG}	2.375	2.5	2.625	V
ESD (human body model)	JEDEC JS-001-2012	ESD _{HBM}			2000	V
ESD (charged device model)	JEDEC JESD22-C101E	ESD _{CDM}			500	V

Notes:

1. Exceeding maximum ratings may shorten the useful life of the device.

2. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or at any other conditions beyond those indicated under the DC Electrical Characteristics is not implied. Exposure to Absolute-Maximum-Rated conditions for extended periods may affect device reliability or cause permanent device damage.

Table 3 Operating Temperature

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Ambient temperature		ТА	-40	-	+105	°C
Junction temperature		TJ			+125	°C

Table 4 DC Electrical Characteristics

Parameter	Condition	Symbol	Min	Тур	Max	Units
	1.8 V range: ±5%		1.71	1.80	1.89	V
Supply Voltage	2.5 V range: ±5%	V _{DD}	2.375	2.50	2.625	V
	3.3 V range: ±10%		2.97	3.3	3.63	V
Supply Current	LVPECL			68		
(Output Enabled)	LVDS			47		
	LVDS-Boost			51		mA
	HCSL (Far End Termination)			59		
	HCSL-LP			50		
Ambient Temperature		Т _{АМВ}			105	°C
		Viн	0.7x VDD			V
		VIL			0.3xVDD	V
Output Enable	Output Disable Time, FCLK > 10 MHz	ΤD		1us+ 3clock cycles		uS
	Output Enable Time, FCLK > 10 MHz	TE		1us+ 3clock cycles		uS
Power Up Time				15		ms

Table 5 Output RMS Jitter [AU5260]

Parameter	Conditions	Symbol	Min	Тур	Max	Units
RMS Jitter for 12 kHz – 20 MHz Integration Bandwidth	Fout = 622.08 MHz					
	Fout = 156.25 MHz	RMSJIT		110		ts rms

Notes:

1. The RMS Jitter data is based on the simulation results. Final data will be populated based on lab Characterization.



Parameter	Conditions	Symbol	Min	Тур	Мах	Units
RMS Jitter for 12 kHz – 20 MHz Integration Bandwidth	F _{OUT} = 622.08 MHz	RMSJIT				
	F _{OUT} = 156.25 MHz			85		ts rms

Table 6 Output RMS Jitter [AU5265]

Notes:

1. The RMS Jitter data is based on the simulation results. Final data will be populated based on lab Characterization.

Table 7 Clock Output Phase Noise [AU5260]					
Offset Frequency	156.25 MHz LVDS	622.08 MHz LVDS	Units		
1 kHz	-118.5	-106.5			
10 kHz	-128.8	-116.8			
100 kHz	0 kHz -139.5 -127.5		dDo/Uz		
1 MHz	-152.2	-140.2			
10 MHz	-167.2	-157.5			
20 MHz	-170.5	-162.7			
Offset Frequency	156.25MHz LVPECL	622.08 MHz LVPECL	Units		
1 kHz	-118.5	-106.5			
10 kHz	-128.8	-116.8			
100 kHz	-139.5	-127.5	dPo/Uz		
1 MHz	-152.2	-140.2			
10 MHz	-165.7	-157.4			
20 MHz	-169.8	-162.6			

Notes:

1. The Clock Output Phase Noise data is based on the simulation. Final Phase Noise data will be populated based on lab Characterization.

Table 8 Clock Output Phase Noise [AU5265]

Offset Frequency	156.25 MHz LVDS	622.08 MHz LVDS	Units
1 kHz	-120.7	-108.7	
10 kHz	-132.7	-120.7	
100 kHz	-143.6	-131.6	dDa/Uz
1 MHz	-151.8	-139.8	
10 MHz	-167.9	-159.1	
20 MHz	-170.6	-162.9	
Offset Frequency	156.25MHz LVPECL	622.08 MHz LVPECL	Units
1 kHz	-120.7	-108.7	
10 kHz	-132.6	-120.7	
100 kHz	-143.6	-131.6	dPo/Uz
1 MHz	-151.7	-139.8	
10 MHz	-166.3	-158.8	
20 MHz	-169.8	-162.9	

Notes:

1. The Clock Output Phase Noise data is based on the simulation. Final Phase Noise data will be populated based on lab Characterization.

Table 9 Power Supply Rejection

Parameter	Conditions	Symbol	Min	Тур	Мах	Units
	100 kHz Sine Wave					
F _{OUT} = 156.25 MHz	200 kHz Sine Wave	PSRR _{VDD}		-85		dDa
	500 kHz Sine Wave					uрс
	1 MHz Sine Wave					



Notes:

- 1. The PSRR is measured with a 50 mVpp sinusoid in series with the supply and checking the spurious level relative to the carrier on the output in terms of phase disturbance impact.
- 2. Output PSRR measured with LVDS standard which are the recommended standards for AC Coupled terminations.
- 3. The PSRR data is provided based on simulation worst case numbers. Final data will be provided based on lab characterization.

Parameter	Conditions	Symbol	Min	Тур	Max	Unit		
DC Electrical Specifications – LVDS Outputs (VDD = 1.8 V, 2.5 V or 3.3 V range)								
Output Common-Mode Voltage	VDD = 2.5 V or 3.3 V range	V _{OCM}		1.2		V		
Output Common-Mode Voltage	VDD = 1.8 V	V _{OCM}		0.85				
AC Electrical Specificati	ons (LVPECL, LVDS, HCSL	Far End Ter	mination): Fou	t = 156.25 MHz				
Clock Output Frequency		f _{OUT}	0.2		1000	MHz		
LVPECL Output Rise/Fall Time	20% to 80% of AC levels. Measured at 156.25 MHz for LVPECL outputs.	t _{RF}			350	ps		
LVDS Output Rise/Fall Time	20% to 80% of AC levels. Measured at 156.25 MHz for LVDS outputs.	t _{RF}			350	ps		
LVDS-Boost Output Rise/Fall Time	20% to 80% of AC levels. Measured at 156.25 MHz for LVDS outputs.	t _{RF}			350	ps		
HCSL Far End Termination Output Rise/Fall Time	20% to 80% of AC levels. Measured at 156.25 MHz for HCSL outputs.	t _{RF}			350	ps		
Output Duty Cycle	Measured at differential 50% level, 156,25 MHz	topc	45	50	55	%		
LVPECL Output	Measured at 156.25M	VP		750				
LVDS Output differential peak	Measured at 156.25M Output	VP		400		-		
LVDS-Boost Output differential peak	Measured at 156.25M Output	VP		790		mV		
HCSL Far End Termination Output differential peak Measured at 156. Output		VP		800				
AC Electrical Specificati	ons (HCSL – LP)							
Slew Rate	Scope Averaging on	dV/dt	1		4	V/ns		
Slew Rate Matching	Single-ended measurement.	ΔdV/dt			20	%		
Maximum Voltage	Measurement on single ended signal	V _{MAX}		850		mV		
Minimum Voltage	using absolute value. (Scope averaging off).	V _{MIN}		0		mV		
Crossing Voltage (abs)	Scope averaging off.	V _{cross_abs}		430		mV		
Crossing Voltage (var)	Scope averaging off.	Δ -V _{cross}		9.6		mV		
Differential Impedance		Z _{DIFF}		85/100		Ω		

Table 10 Output Clock Specifications



Notes: Convention for Wave Forms





3 Serial Programming Interface Description

The chip settings can be reconfigured using the I2C serial programming interface.

3.1 I2C protocol

Pin configuration of serial interface in I2C slave mode is as follows.

- SCL
- SDA

The device uses the SDA and SCL pins for a 2-wire serial interface that operates up to 400 Kb/s in Read and Write modes. It complies with the I2C bus standard. The I2C access protocol in device is both random and sequential access for Write and Read modes.

The I2C serial interface can operate at either Standard rate (100 Kbps) or Fast rate (400 Kbps).

The default I2C address will be 0x55, The Device will support to configure any I2C address through One Time Programming.

Rea	d Operation - Sin	gle B	yte					
S	Slave Addr [6:0]	0	A	Reg Addr [7:0] A	Р			
S	Slave Addr [6:0]	1	Α	Data [7:0] N P				
	Read Open	ratio	n - Bu	rst (Auto Address Incre	ement)			
S	Slave Addr [6:0]	0	A	Reg Addr [7:0] A	Р			
S	Slave Addr [6:0]	1	A	Data [7:0] A Da	ata [7:0] N P			
$\mathbf{Reg} \mathbf{Addr} + 1$								
	Host 🔶 A	.U526	бх	·	0			
Host \rightarrow AU526x								
1- Read, 0 - Write, A - Acknowledge, N - Not Acknowledge, S - Start Condition, P - Stop Condition								
Eigure 3 12C Poad Operation								



Vrite Operation - Single Byte									
S	Slave Addr	0	A	Reg Addr [7:0]	A	Data [7:0]	A	Р	
Vrite Operation - Burst (Auto Address Increment)									
S	Slave Addr [6:0] () [A Reg Addr [7:0	0]	Data [7:0] A			
Reg Addr + 1									
Host \leftarrow AU526x									
• Read, 0 - Write, A – Acknowledge (SDA LOW), N - Not Acknowledge (SDA HIGH), S - Start Condition, P - Stop Condition									

3.1.1 Single Byte Write

- The master initiates the transaction by issuing a start condition, writes 7-bit slave address and then the read/write bit is written as 0 (write)
- The slave acknowledges by driving zero on the bus
- The master then writes the 8-bit register map address
- The slave acknowledges by driving zero on the bus
- The master then writes the 8-bit data to be written to the register map address specified
- The slave acknowledges by driving zero on the bus
- o The master ends the transaction by issuing a stop condition

3.1.2 Multi Byte Write

- The master initiates the transaction by issuing a start condition, writes 7-bit slave address and then the read/write bit is written as 0 (write)
- The slave acknowledges by driving zero on the bus
- \circ $\,$ $\,$ The master then writes the 8-bit register map address $\,$
- The slave acknowledges by driving zero on the bus
- The master then writes the 8-bit data to be written to the register map address specified
- \circ $\;$ The slave acknowledges by driving zero on the bus and increment the address by 1 $\;$
- The master continuously writes the 8-bit data to the slave and the slave will acknowledge by driving zero for every byte.
- The master ends the transaction by issuing a stop condition



3.1.3 Single Byte Read

- The master initiates the transaction by issuing a start condition, writes 7-bit slave address and then the read/write bit is written as 0 (write)
- The slave acknowledges by driving zero on the bus
- The master then writes the 8-bit register map address
- The slave acknowledges by driving zero on the bus
- The master ends the transaction by issuing a stop condition
- The master re-initiates the transaction by issuing a start condition, writes 7-bit slave address and then the read/write bit is written as 1 (read)
- o The slave then writes the 8-bit data to be written to the register map address specified
- The master does not acknowledge this transaction as the slave may assume a multi-byte read operation and there is a risk of slave holding the bus low
- The master ends the transaction by issuing a stop condition

3.1.4 Multi Byte Read

The multi-byte read mode is used to read a continuous segment of the register map. The multi-byte read is faster than performing multiple single byte reads as the device address and register map address need not be specified for every byte read from the register map

- The master initiates the transaction by issuing a start condition, writes 7-bit slave address and then the read/write bit is written as 0 (write)
- o The slave acknowledges by driving zero on the bus
- The master then writes the 8-bit register map address
- The slave acknowledges by driving zero on the bus
- The master ends the transaction by issuing a stop condition
- The master re-initiates the transaction by issuing a start condition, writes 7-bit slave address and then the read/write bit is written as 1 (read)
- The slave then writes the 8-bit data to be written to the register map address specified
- o The master acknowledges by driving zero on the bus
- The slave automatically increments the register map address and writes the data in at that address to the bus and the master acknowledges
- o When all bytes of data are read, master ends the operation by not acknowledging the last read
- The master then ends the transaction by issuing a stop condition



3.1.5 I2C Bus Timing Specifications

Table 11 I2C Bus Timing Specification

Description	Symbol	Standard Mode		Fast Mode		Unito	
Description	Symbol	Min	Max	Min	Max	Units	
SCLK clock frequency	fscl	-	100	-	400	kHz	
Hold time START condition	thd:sta	0.4	-	0.6	-	μs	
Low period of the SCK clock	tLOW	4.7	-	1.3	-	μs	
High period of the SCK clock	tніgн	4.0	-	0.6	-	μs	
Setup time for a repeated START	toutora	47		0.6		116	
condition	ISU:STA	4.7	_	0.0	_	μο	
Data hold time	thd:dat	300	-	300	-	ns	
Data setup time	tsu:dat	100	-	-	-	ns	
Rise time	t _R	_	1000	-	300	ns	
Fall time	t⊧	—	300	-	300	ns	
Setup time for STOP condition	tsu:sto	4.0	-	0.6	-	μs	
Bus-free time between STOP and	tour	47		13	_	116	
START conditions	(BOF	4.7		1.5	_	μο	
Data valid time	tvd;dat	-	3.45	-	0.9	μs	
Data valid acknowledge time	t _{VD;ACK}	-	0.9	I	0.9	μs	

Note:

In I2C mode, the serial data and clock have an on-chip 25 kΩ pull up resistor to VDDIO. Please refer Figure 5 for the nomenclature of these parameters.



Figure 5 I2C Timing Waveform



4 Package Information

Package Information to be updated in next revision

Figure 6 Package Diagram (3.2 mm x 2.5 mm)

Package Information to be updated in next revision

Figure 7 Package Diagram (5.0 mm x 3.2 mm)



5 Output Termination Information



Figure 8 LVPECL Output Driver used with traditional DC Coupled LVPECL receiver



VDD	R1	R2
2.5 V	250 Ω	62.5 Ω
3.3 V	127 Ω	82.5 Ω

Figure 9 LVPECL Output Driver with DC Coupled LVPECL receiver: Thevenin Equivalent















Figure 11 LVDS Output Driver used with AC Coupled terminations for various receivers



Figure 12 HCSL DC Coupled – Low-Power (HCSL-LP)





Figure 13 HCSL DC Coupled - Far End Termination



Figure 14 Output Driver with AC Coupled CML receiver



6 Ordering Information



Figure 15 Ordering Information

Note: Please contact Aurasemi sales for 5.0 mm x 7.0 mm and 2.5 mm x 2.0 mm packages.



7 Revision History

Table 12 Revision History

Version	Date	Description	Author
0.1	26 th Sep 2022	AU526x Advanced Datasheet First Draft Created	Aurasemi



IMPORTANT NOTICE AND DISCLAIMER

AURASEMI PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers skilled in the art designing with Aurasemi products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Aurasemi grants you permission to use these resources only for development of an application that uses Aurasemi products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Aurasemi intellectual property or to any third-party intellectual property. Aurasemi disclaims responsibility for, and you will fully indemnify Aurasemi and its representatives against, any claims, damages, costs, losses, or liabilities arising out of your use of these resources. Aurasemi products are provided only subject to Aurasemi Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Aurasemi resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

Contact Information

For more information visit www.aurasemi.com For sales related information please send an email to sales@aurasemi.com

Trademarks

Aurasemi and Aurasemi Logo are trademarks of Ningbo Aura Semiconductor Private Limited. All referenced brands, product names, service names and trademarks are the property of their respective owners.